

# 3D IC Probe Card Solutions



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### Outline

- Trends and Challenges of IC Packaging & Testing
- Heterogeneous Integration Probe Card (HIPC) for 3D IC Test
- CHPT's HIPC Solutions
- Summary
- Follow-On Work

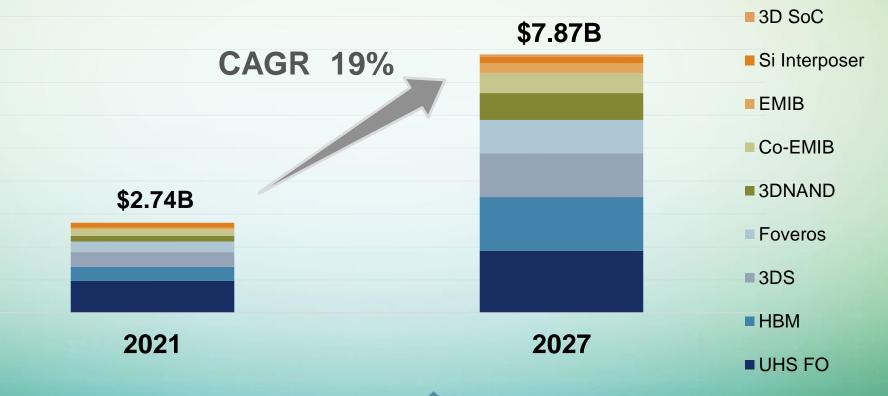




### Trends and Challenges of IC Packaging & Testing

#### 2021-2027 High-End Packaging Market

The high-end packaging market size is expected to reach \$7.87B by 2027, rising at a market growth of 18.6% CAGR.



Source: Yole (2022) \ CHPT

Author: Alan Su

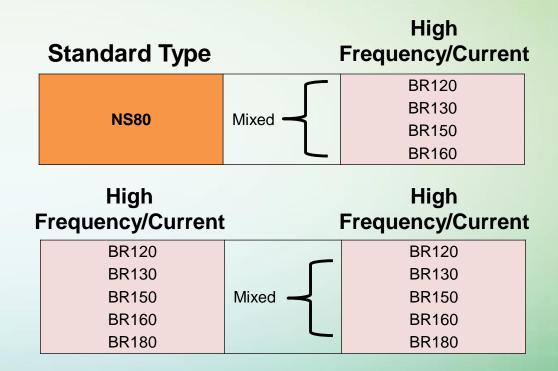
#### **HIPC for 3D IC Test**

- CHPT HIPC Provides High Speed Testing Solutions for Wafer Sorting
  - Structural Optimization: How to reinforce probe needle, probe needle profile and guide plate through mechanical simulation?
  - Contact Force Control: How to optimize probe pin's characteristics? 2 different diameter probe needles offer the same contact force to meet probe mark spec.
  - Bandwidth Improvement: Bandwidth is the fundamental factor for successful high speed testing. How do we achieve desired bandwidth based on different bump/pad pattern?

### **HIPC Solutions: Mixed Needle**

CHPT's HIPC Solutions Can Work Stably in Bandwidth Testing Projects

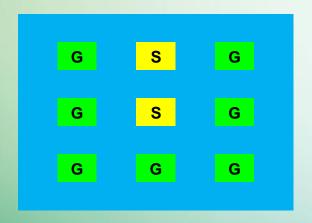
Specification	BR Series	NS Series
Applicable Pitch (um)	110~180	50~100
Contact Force (@ 4mils O.D.)(g)	2.0~4.3	1.5~4.0
Current Carrying Capability (mA) (ISMI 2009)	1,800~2,400	500~1,200
Temperature (°C)	-40~150	-40~150



# **HIPC Solutions: Case Study**

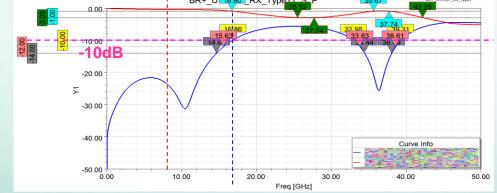
Mixed Needle Design Practical Case Sharing

#### **Needle Arrangement**



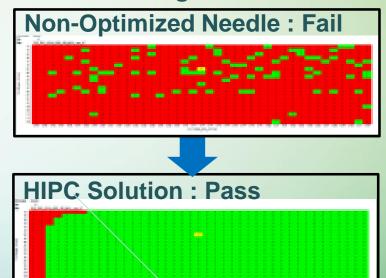
# **Spec.** Requirements vs. **Electrical Simulation Results**





Simulation results:16.8GHz@-10dB

#### **Electrical Diagram: Shmoo**



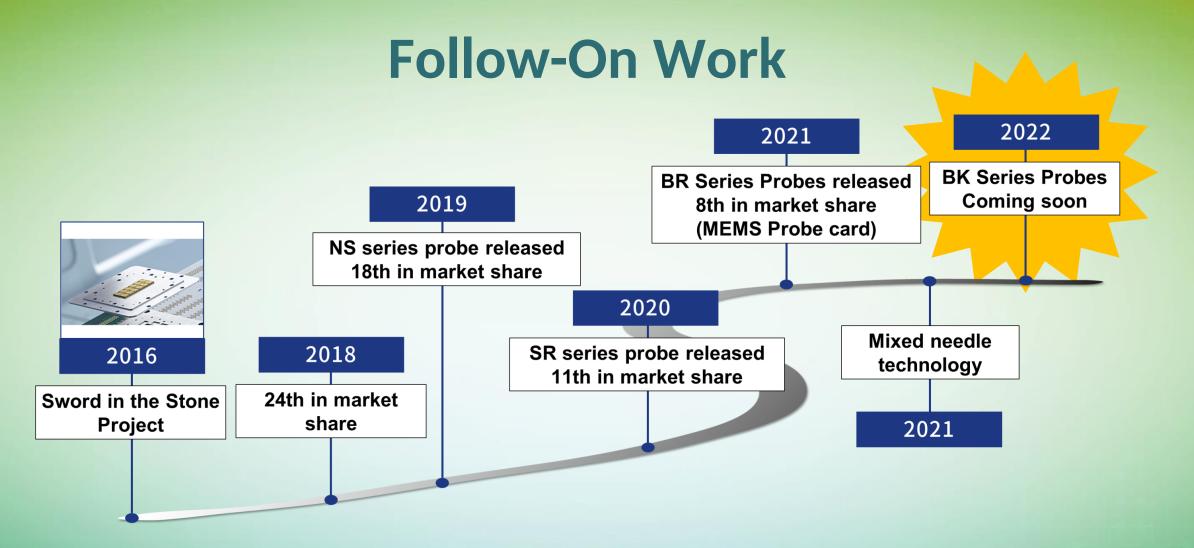
# Summary

- Semiconductor 3D IC market growth at 18.6% CAGR.
- Advanced packaging technology highlights the importance of HIPC.
- Our product from PCB, interposer to probe head are AI optimized with smart manufacturing.
- CHPT's high-quality HIPC solution meets the requirements of high pin count, high current and optimized bandwidth at the different pitches.









BK series needles have better CCC and excellent bandwidth characteristics. The single-pin CCC can reach 2.5A and the bandwidth can reach more than 28GHz under proper arrangement.